

# ACKNOWLEDGEMENT RECEIPT

Electronic Version 1.1

Stylesheet Version v1.1.1

## Title of Invention

METHODS OF THINNING A SILICON WAFER USING HF AND  
OZONE

Submission Type : Information Disclosure  
Statement

Application Number:

10/631376



EFS ID:

93253

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Attorney Docket Number: 54008.8033.US00

Timestamp: 2005-09-22 19:55:56 EDT

From: us

File Listing:

Doc. Name	File Name	Size (Bytes)	Date Produced (yyyymmdd)
us-fee-sheet	54008.8033.US00-usfees.xml	1488	2005-09-22
us-fee-sheet	us-fee-sheet.xml	25930	2005-09-22
us-fee-sheet	us-fee-sheet.dtd	11968	2005-09-22
us-ids	54008.8033.US00-usidst.xml	1174	2005-09-22
us-ids	us-ids.dtd	7763	2005-09-22
us-ids	us-ids.xml	12026	2005-09-22
package-data	54008.8033.US00-pkda.xml	2252	2005-09-22
package-data	package-data.dtd	27025	2005-09-22
package-data	us-package-data.xml	19263	2005-09-22
Total files size		108889	

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